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IMPROVED COMPRESSION ASSEMBLED ELECTRONIC PACKAGE HAVING A PLASTIC MOLDED INSULATION RING

ABSTRACT OF THE DISCLOSURE

A compression assembled semiconductor package for housing a power semiconductor die which includes two major pole pieces in intimate electrical contact with respective major electrodes of a power semiconductor die. The package includes a plastic molded insulation ring disposed around the power semiconductor die. The pole pieces are secured to respective ends of the plastic molded insulation ring. One of the pole pieces may include an annular flange that penetrates the plastic molded insulation ring from an interior wall thereof and is embedded in its body. The annular flange preferably comprises a projection having a squared tab and circular distal end that is received by a receiving groove having a notch (to receive the squared tab) and a cavity (to receive the distal end).